

## FNK N-Channel Enhancement Mode Power MOSFET

### Description

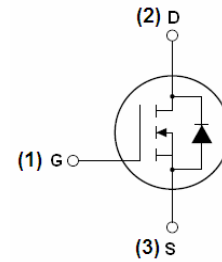
The FNK03N03 uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications.

### General Features

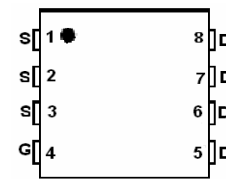
- $V_{DS} = 30V, I_D = 100A$   
 $R_{DS(ON)} < 3.2m\Omega @ V_{GS} = 10V$  (Typ:  $2.5m\Omega$ )
- High density cell design for ultra low  $R_{DS(ON)}$
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high  $E_{AS}$
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

### Application

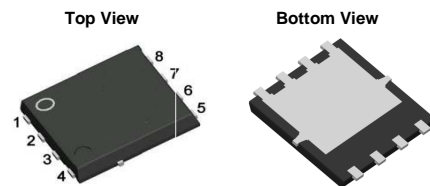
- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply



Schematic diagram



Marking and pin assignment



DFN5X6

### Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
FNK03N03	FNK03N03	DFN5x6	-	-	-

### Absolute Maximum Ratings ( $T_A = 25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	100	A
Drain Current-Continuous ( $T_C = 100^\circ C$ )	$I_D (100^\circ C)$	70	A
Pulsed Drain Current	$I_{DM}$	400	A
Maximum Power Dissipation	$P_D$	110	W
Single pulse avalanche energy (Note 5)	$E_{AS}$	350	mJ
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 175	$^\circ C$

## Thermal Characteristic

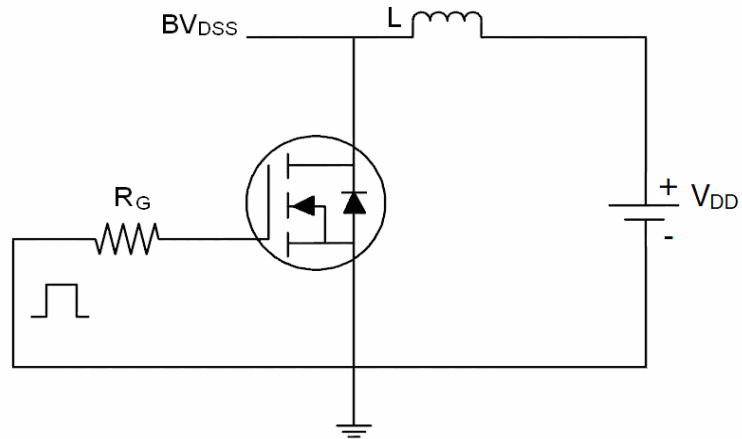
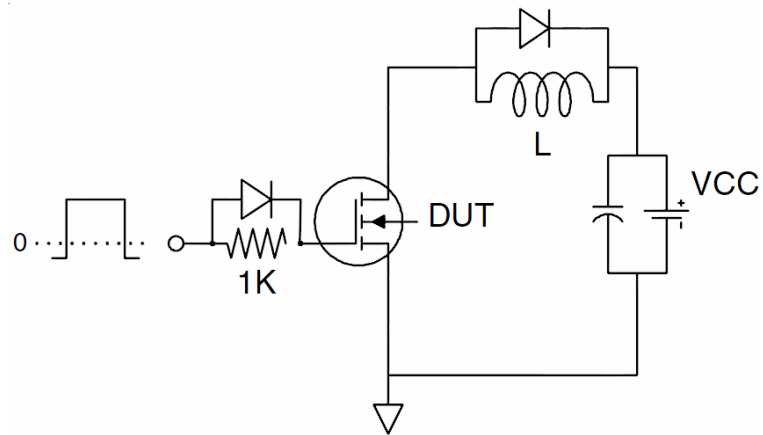
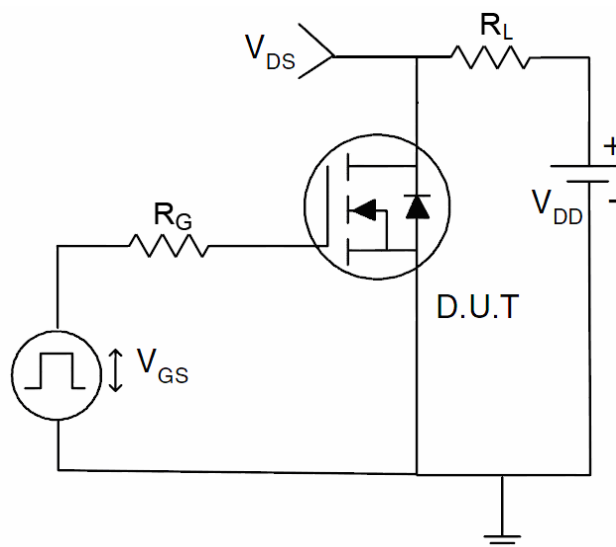
Thermal Resistance, Junction-to-Case <sup>(Note 2)</sup>	$R_{\theta JC}$	1.36	$^{\circ}\text{C/W}$
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## Electrical Characteristics ( $T_A=25^{\circ}\text{C}$ unless otherwise noted)

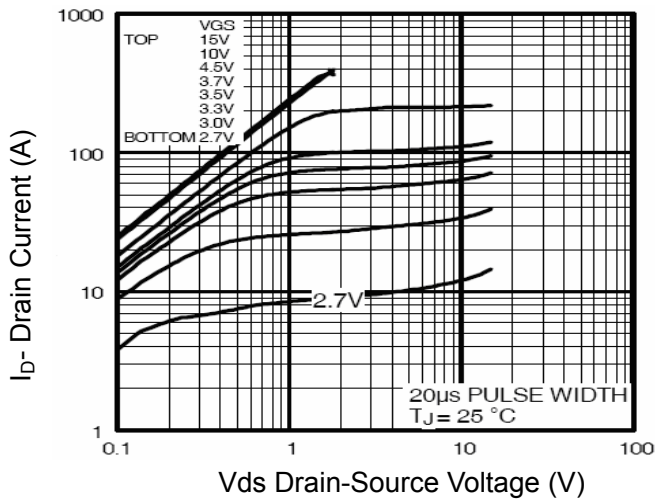
Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	30	-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V	-	-	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1	1.6	3	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =20A	-	2.5	3.2	mΩ
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =10V, I <sub>D</sub> =20A	50	-	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, F=1.0MHz		5950		PF
Output Capacitance	C <sub>oss</sub>			800		PF
Reverse Transfer Capacitance	C <sub>rss</sub>			600		PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =15V, I <sub>D</sub> =60A V <sub>GS</sub> =4.5V, R <sub>GEN</sub> =1.8Ω	-	11	-	nS
Turn-on Rise Time	t <sub>r</sub>		-	160	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>		-	25	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	60	-	nS
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =15V, I <sub>D</sub> =30A, V <sub>GS</sub> =10V		70		nC
Gate-Source Charge	Q <sub>gs</sub>			8.8		nC
Gate-Drain Charge	Q <sub>gd</sub>			16.3		nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =20A	-	-	1.2	V
Diode Forward Current (Note 2)	I <sub>S</sub>	-	-	-	100	A
Reverse Recovery Time	t <sub>rr</sub>	T <sub>J</sub> = 25°C, I <sub>F</sub> = 60A di/dt = 100A/μs (Note3)	-	56	-	nS
Reverse Recovery Charge	Q <sub>rr</sub>		-	110	-	nC
Forward Turn-On Time	t <sub>on</sub>	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

## Notes:

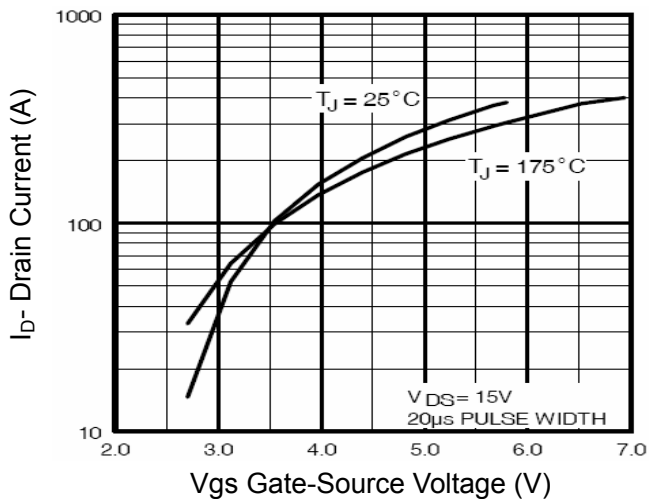
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production
5. EAS condition:  $T_J=25^{\circ}\text{C}, V_{DD}=15V, V_G=10V, L=0.5mH, R_g=25\Omega$

**Test circuit**
**1)  $E_{AS}$  test Circuits**

**2) Gate charge test Circuit:**

**3) Switch Time Test Circuit:**


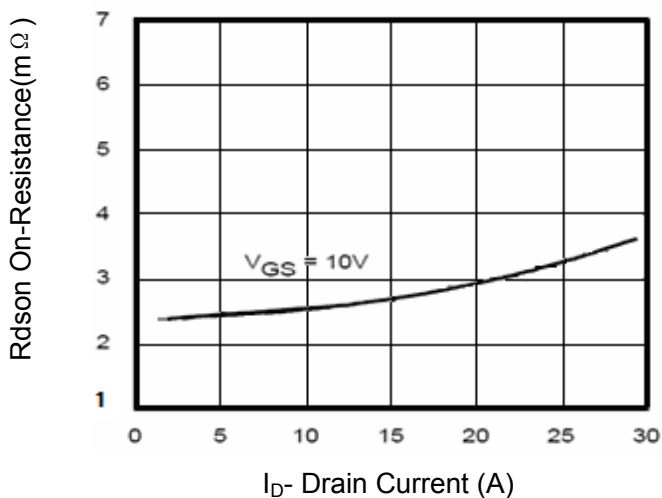
## Typical Electrical and Thermal Characteristics (Curves)



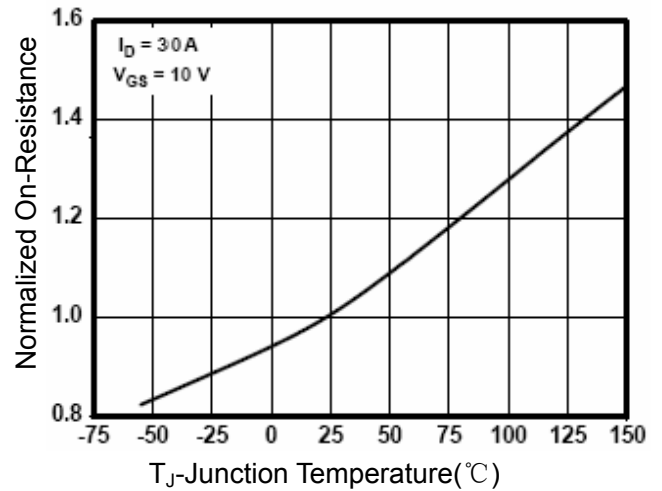
**Figure 1 Output Characteristics**



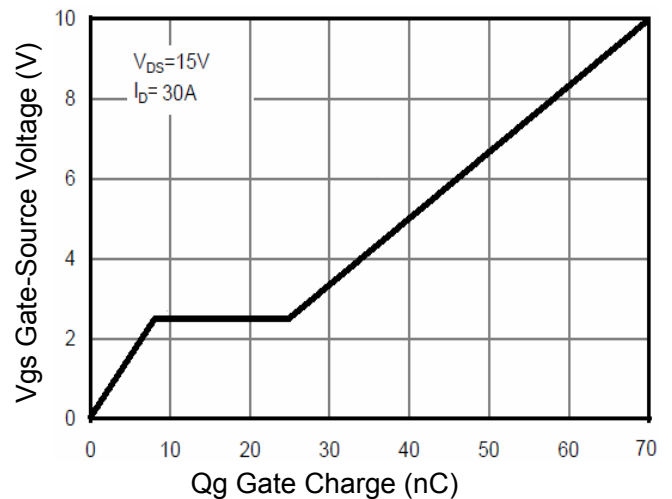
**Figure 2 Transfer Characteristics**



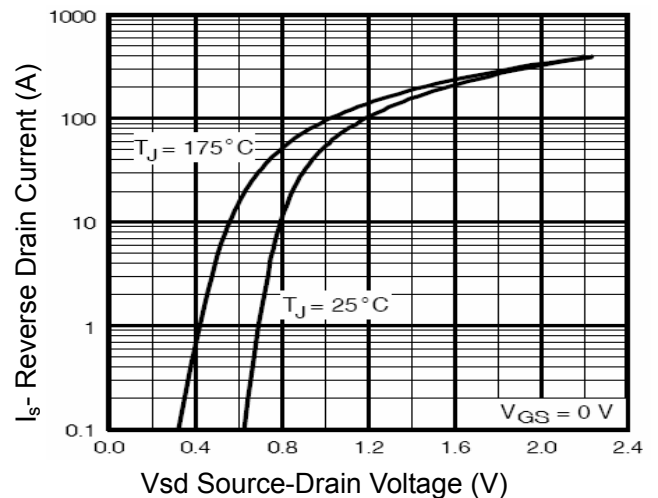
**Figure 3  $R_{DS(on)}$ - Drain Current**



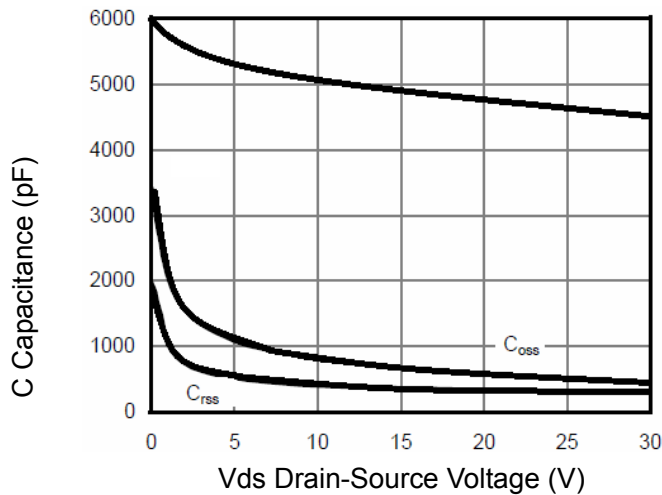
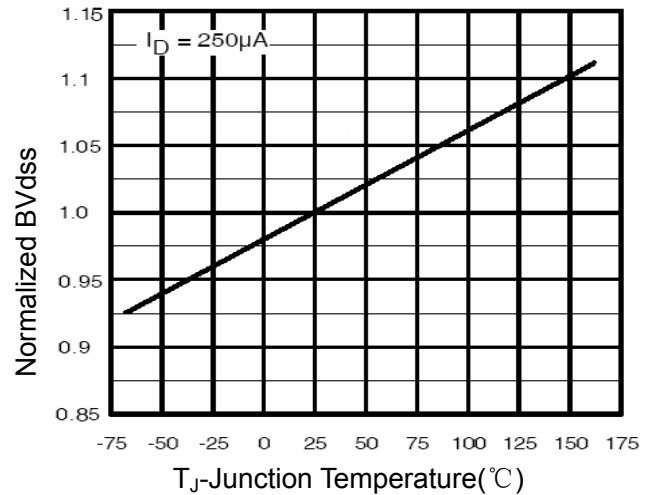
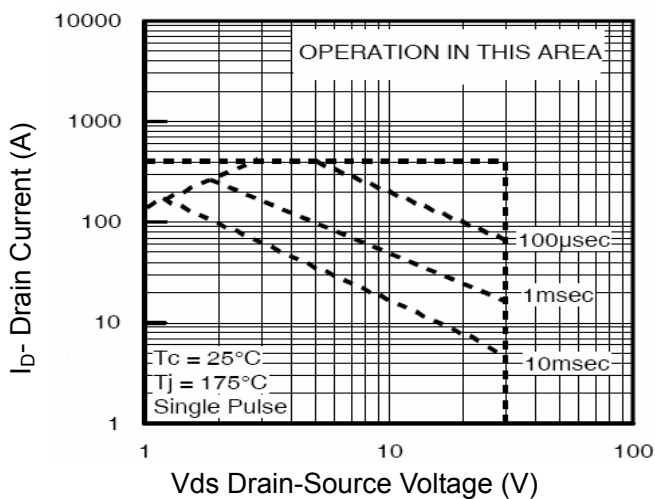
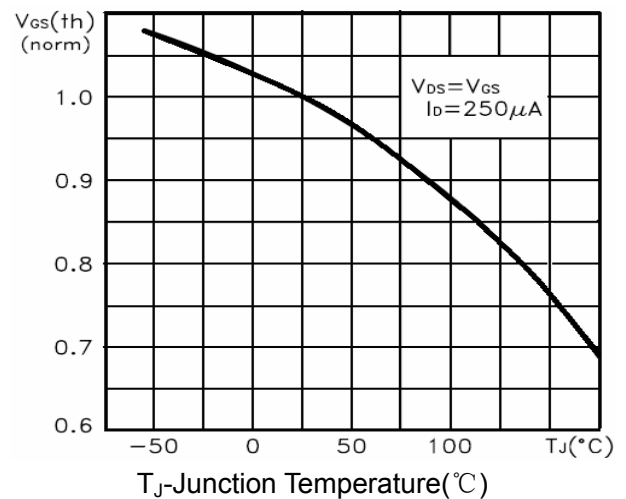
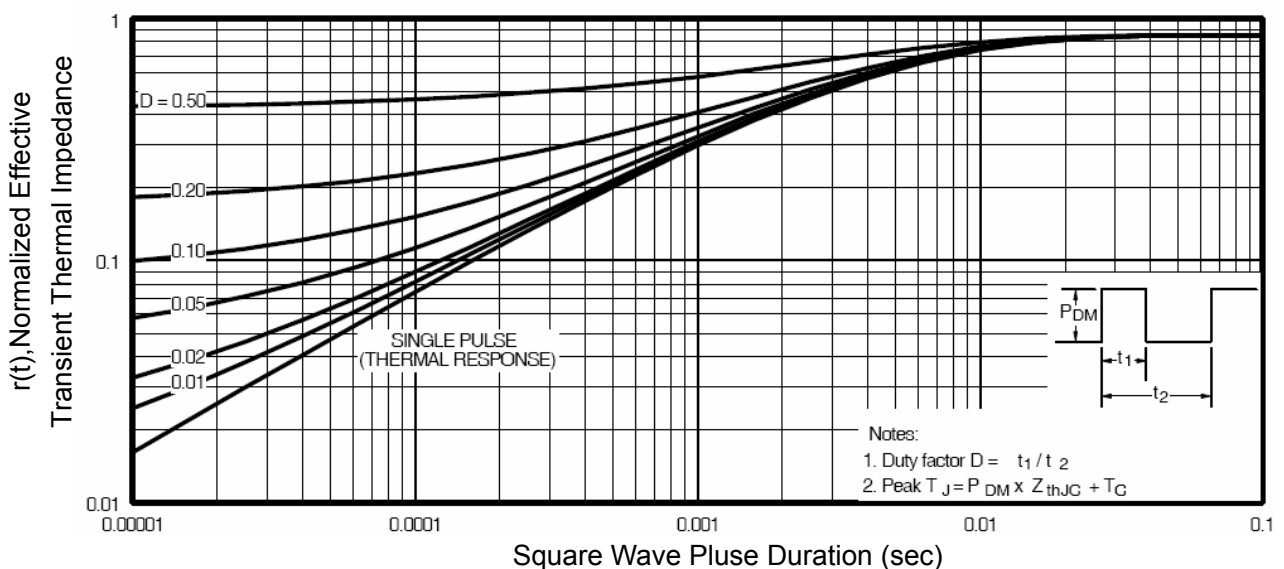
**Figure 4  $R_{DS(on)}$ -Junction Temperature**



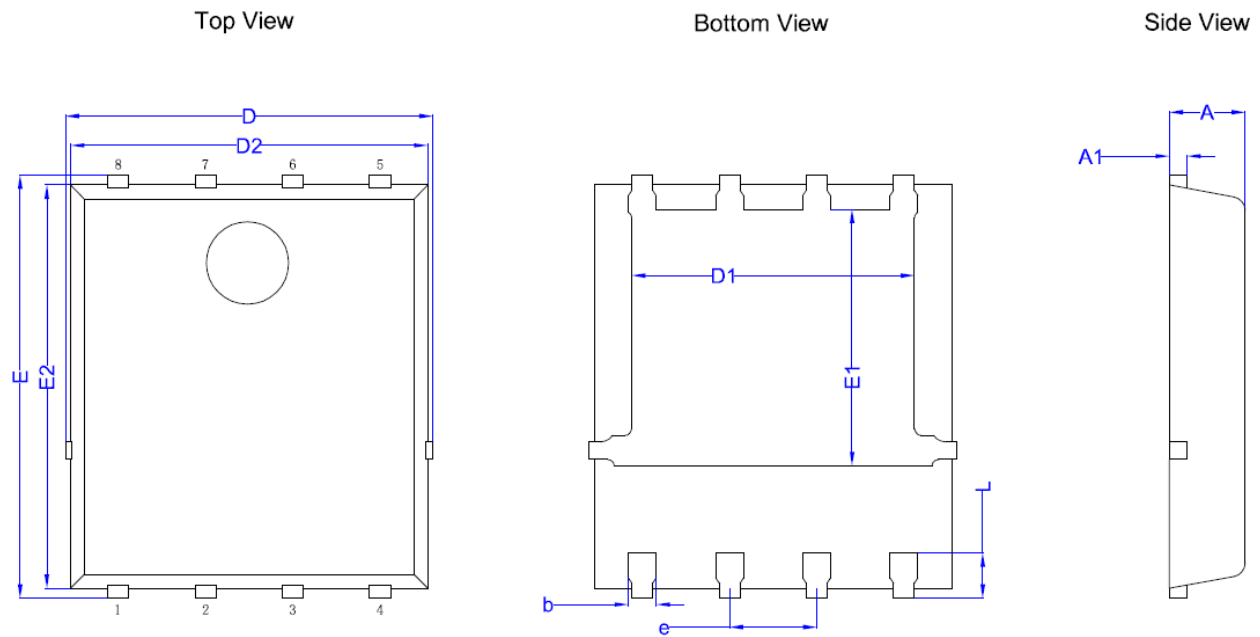
**Figure 5 Gate Charge**



**Figure 6 Source- Drain Diode Forward**


**Figure 7 Capacitance vs Vds**

**Figure 9 BV<sub>DSS</sub> vs Junction Temperature**

**Figure 8 Safe Operation Area**

**Figure 10 V<sub>GS(th)</sub> vs Junction Temperature**

**Figure 11 Normalized Maximum Transient Thermal Impedance**

## DFN5X6-8L Package Information



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	1.00	1.10	1.20
A1	0.254 BSC		
D	5.15	5.35	5.55
E	5.95	6.15	6.35
D1	3.92	4.12	4.32
E1	3.52	3.72	3.92
D2	5.00	5.20	5.40
E2	5.66	5.86	6.06
e	1.27BSC		
b	0.31	0.41	0.51
L	0.56	0.66	0.76

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